

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
HUI WANG	03/30/2018
FUFA CHEN	03/30/2018
FUPING CHEN	04/04/2018
JIAN WANG	04/02/2018
XI WANG	03/30/2018
XIAOYAN ZHANG	03/30/2018
YINUO JIN	03/30/2018
ZHAOWEI JIA	04/16/2018
LIANGZHI XIE	04/18/2018
JUN WANG	03/30/2018
XUEJUN LI	03/30/2018
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	ACM RESEARCH, INC.
<b>Street Address:</b>	BUILDING 4, NO. 1690, CAI LUN ROAD
<b>Internal Address:</b>	ZHANGJIANG HIGH-TECH PARK, PUDONG DISTRICT
<b>City:</b>	SHANGHAI
<b>State/Country:</b>	CHINA
<b>Postal Code:</b>	201203
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	15814246
<b>CORRESPONDENCE DATA</b>	
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PATENT

<b>ATTORNEY DOCKET NUMBER:</b>	1106989.00012
<b>NAME OF SUBMITTER:</b>	MIN WU
<b>SIGNATURE:</b>	/Min Wu/
<b>DATE SIGNED:</b>	05/09/2018
<b>Total Attachments: 2</b> source=1106989_00012_Assignment#page1.tif source=1106989_00012_Assignment#page2.tif	

**ASSIGNMENT**



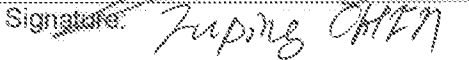
**WHEREAS**, we, Hui Wang, Fufa Chen, Fuping Chen, Jian Wang, Xi Wang, Xiaoyan Zhang, Yinuo Jin, Zhaowei Jia, Liangzhi Xie, Jun Wang and Xuejun Li, have invented certain new and useful inventions disclosed in U.S. Application No. 15/814,246, entitled "METHOD FOR CLEANING SEMICONDUCTOR WAFERS", filed November 15, 2017 for United States Letters Patent;

**WHEREAS**, ACM Research, Inc., a corporation organized and existing under the laws of the State of Delaware having a place of business at Building 4, No. 1690, Cai Lun Road, Zhangjiang High-Tech Park, Pudong District, Shanghai 201203, China, the ASSIGNEE herein, desires to acquire the entire right to, title to, and interest in said inventions, applications, and Letters Patent to be granted and issued thereon;

**NOW, THEREFORE**, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, we have sold, assigned, transferred and set over, and do hereby sell, assign, transfer, and set over to ASSIGNEE the entire right to, title to, and interest in said inventions, and said application and all applications claiming priority thereto including all utility filings and all divisions, continuations, and continuations-in-part thereof, and all United States Letters Patents which may be granted thereon and all reissues, reexaminations, and extensions thereof, and all priority rights under all available International Agreements, Treaties, and Conventions for the protection of intellectual property in its various forms in every participating country, all national and regional applications deriving therefrom, and all subsequent patents and divisional patents, and all applications for patents (including related rights such as utility-model registrations, inventor's certificates, and the like) heretofore or hereafter filed for improvements in any foreign countries, and all patents (including all continuations, continuations-in-part, divisions, extensions, renewals, substitutes, and reissues thereof) granted for said inventions in any foreign countries; and we hereby authorize and request the United States Commissioner of Patents and Trademarks, and any officials of foreign countries whose duty it is to issue patents on applications as aforesaid, to issue all patents for said improvements to ASSIGNEE in accordance with the terms of this Assignment;

**AND WE HEREBY** covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith;

**AND WE HEREBY** further covenant and agree that we will communicate to ASSIGNEE any facts known to us respecting said inventions, testify in any legal proceeding, sign all lawful papers, execute all documents for subsequent patent filings, make all rightful oaths, and generally do everything possible to aid ASSIGNEE to obtain and enforce proper patent protection for said improvements in all countries.

NAME AND SIGNATURE OF ASSIGNOR		
Name: Hui Wang	Signature: 	Date: 03/30/2018
Name: Fufa Chen	Signature: 	Date: 03/30/2018
Name: Fuping Chen	Signature: 	Date: 04/05/2018

Docket No. 1106989.00012

Name: Jian Wang	Signature: <i>Jian Wang</i>	Date: 2018.4.2.
Name: Xi Wang	Signature: <i>Xi Wang</i>	Date: 2018.3.30
Name: Xiaoyan Zhang	Signature: <i>Xiao Yan Zhang</i>	Date: 2018.3.30
Name: Yinuo Jin	Signature: <i>Yinuo Jin</i>	Date: 2018.3.30
Name: Zhaowei Jia	Signature: <i>Zhaowei Jia</i>	Date: 2018.9.16
Name: Liangzhi Xie	Signature: <i>Liangzhi Xie</i>	Date: 2018.4.18
Name: Jun Wang	Signature: <i>Jun Wang</i>	Date: 2018.3.30
Name: Xuejun Li	Signature: <i>Xuejun Li</i>	Date: 3.30